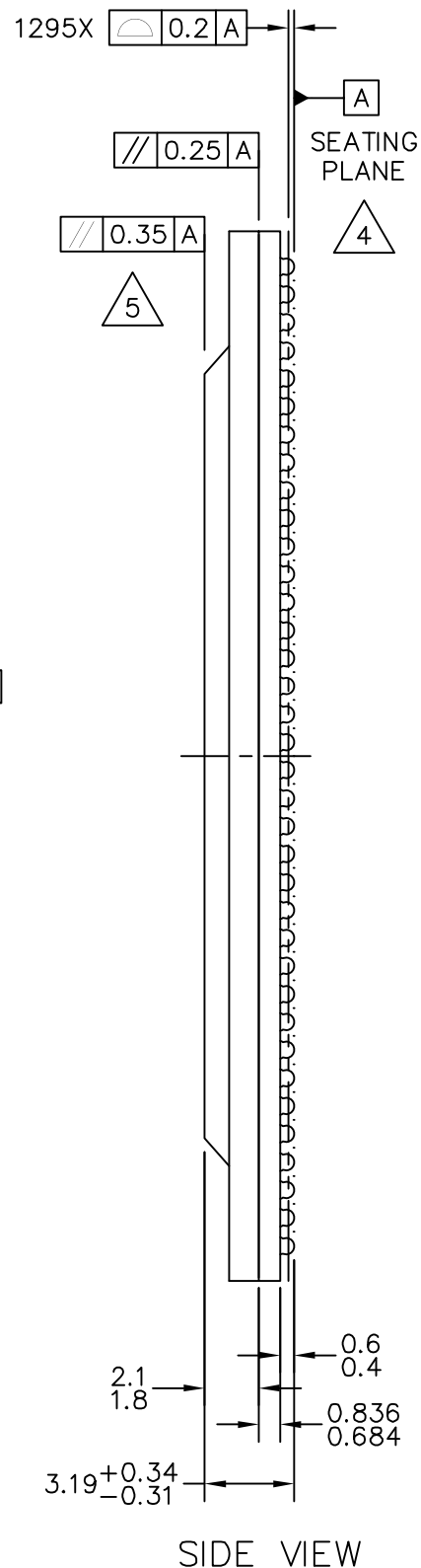
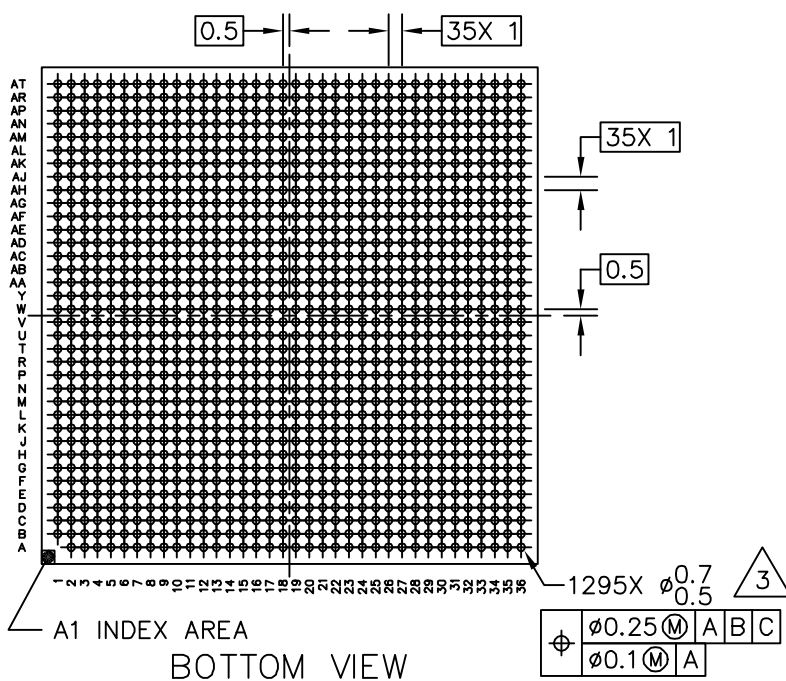
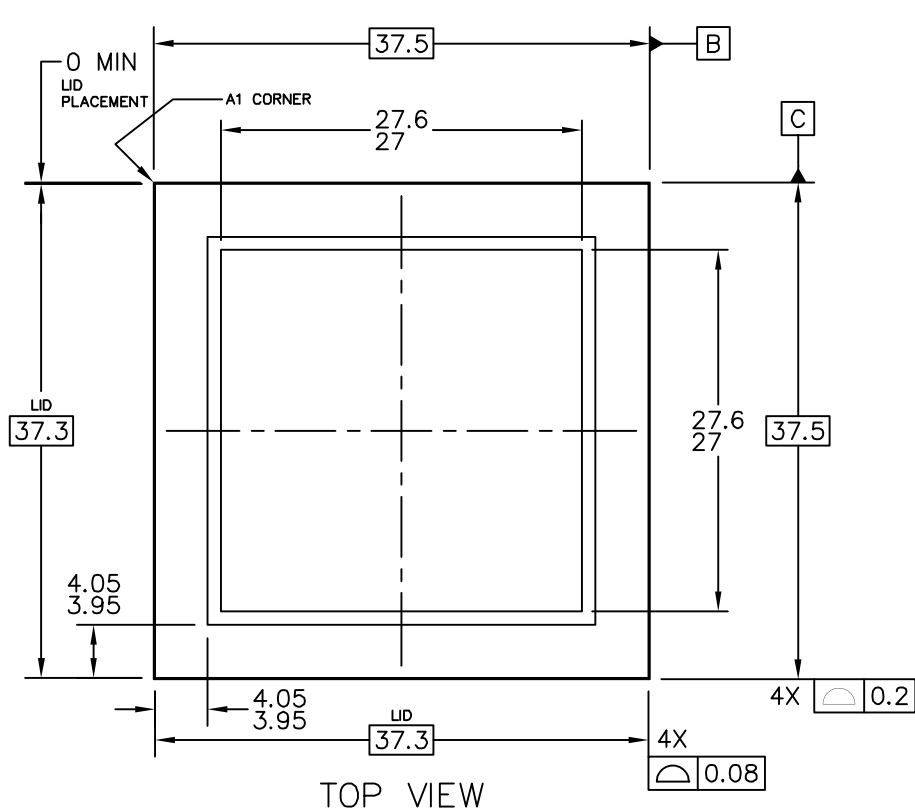




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MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE: 1295 I/O FC PBGA,
37.5 X 37.5 PKG, 1 MM PITCH,
WITH LID

DOCUMENT NO: 98ARE10748D

REV: D

CASE NUMBER: 2040-04

15 JUN 2009

STANDARD: JEDEC MS-034

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

 3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

 4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

 5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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